



Specification Sheet

P/N: Photocoupler

Customer: _____

Mfg P/N: OR-3H7

Date: _____

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1、Features

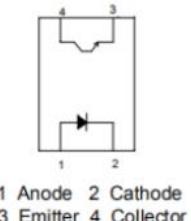
- 1.Current transfer ratio(CTR) : MIN. 50% at $I_F = 5\text{mA}$, $V_{CE} = 5\text{V}$, $T_a=25\text{ }^{\circ}\text{C}$
- 2.High input-output isolation voltage.($V_{ISO}=3,750\text{VRms}$)
3. $V_{CEO} = 80\text{V}$
- 4.Operating Temperature:-55 $^{\circ}\text{C}$ to 115 $^{\circ}\text{C}$
- 5.Lead free, in compliance with RoHS standards



2、Instructions

The or-3h7 series device contains an infrared led and a phototransistor detector.

They are encapsulated in a 4-pin SOP, free of halogens and Sb2O3



3、Application Range

- (1). Mixed PCB substrate requiring high density installation
- (2). Programmable controller
- (3). System apparatus and measuring instruments

4、Max Absolute rated Value (Normal Temperature=25°C)

Parameter		Symbol	Rated Value	Unit
Input	Forward Current	I_F	50	mA
	Peak forward current($t=10\mu\text{s}$)	I_{FM}	1	A
	Reverse Voltage	V_R	6	V
	Power Dissipation	P	70	mW
Output	Collector and emitter Voltage	V_{CEO}	80	V
	Emitter and collector Voltage	V_{ECO}	7	
	Collector Current	I_C	50	mA
	Power Dissipation	P_C	150	mW
Total Power Dissipation		P_{tot}	200	mW
*1 Insulation Voltage		V_{iso}	3750	VRms
Rated Impulse Insulation Voltage		V_{IORM}	630	V
Operating Temperature		T_{opr}	-55 to + 115	°C
Storage Temperature		T_{stg}	-55 to + 150	
*2 Soldering Temperature		T_{sol}	260	

*1. AC For 1 Minute, R.H. = 40 ~ 60%

Isolation voltage shall be measured using the following method.

(1) Short between anode and cathode on the primary side and between collector and emitter on the secondary side

(2) The isolation voltage tester with zero-cross circuit shall be used.

(3) The waveform of applied voltage shall be a sine wave.

*2.soldering time is 10 seconds



5、Opto-electronic Characteristics(Normal Temperature=25°C)

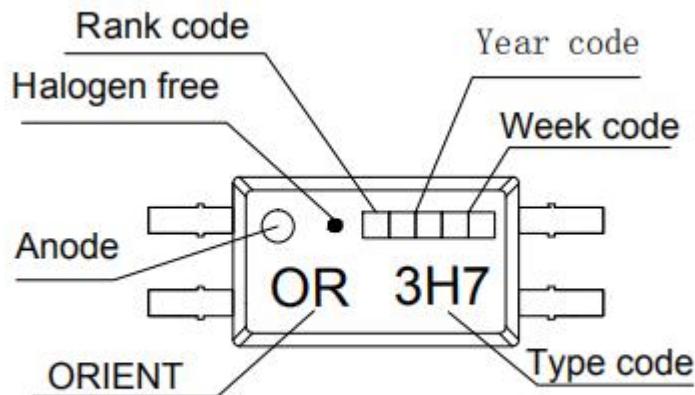
Parameter		Symbol	Condition	Min	Typ.*	Max	Unit
Input	Forward Current	V_F	$I_F=20mA$	---	1.2	1.4	V
	Reverse Voltage	I_R	$V_R=4V$	---	---	10	μA
	Terminal Capacitance	C_t	$V=0, f=1KHz$	---	30	250	pF
Output	Collector Dark Currentt	I_{CEO}	$V_{CE}=20V,$ $I_F=0mA$	---	---	100	nA
	Collector-Emitter Breakdown Voltage	BV_{CEO}	$I_C=0.1mA$ $I_F=0mA$	80	---	---	V
	Emitter-Collector Breakdown Voltage	BV_{ECO}	$I_E=10uA$ $I_F=0mA$	7	---	---	V
(Transforming Characteristics)	*1 Current Transfer Ratio	CTR	$IF=5mA$ $VCE=5V$	50	---	600	%
	Collector Current	I_C		2.5	---	30	mA
	Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$I_F=8mA$ $I_C= 2.4mA$	---	---	0.4	V
	Insulation Impedance	R_{iso}	DC500V 40~60%R.H.	5×10^{10}	1×10^{11}	---	Ω
	Floating Capacitance	C_f	$V=0, f=1MHz$	---	0.6	1	pF
	Response Time	t_r	$V_{CE}=5V, I_C=2mA$	---	2	18	μs
	Descend Time	t_f	$R_L=100\Omega$ $f=100Hz$	---	3	18	μs

- Current Conversion Ratio = $I_C / I_F \times 100\%$

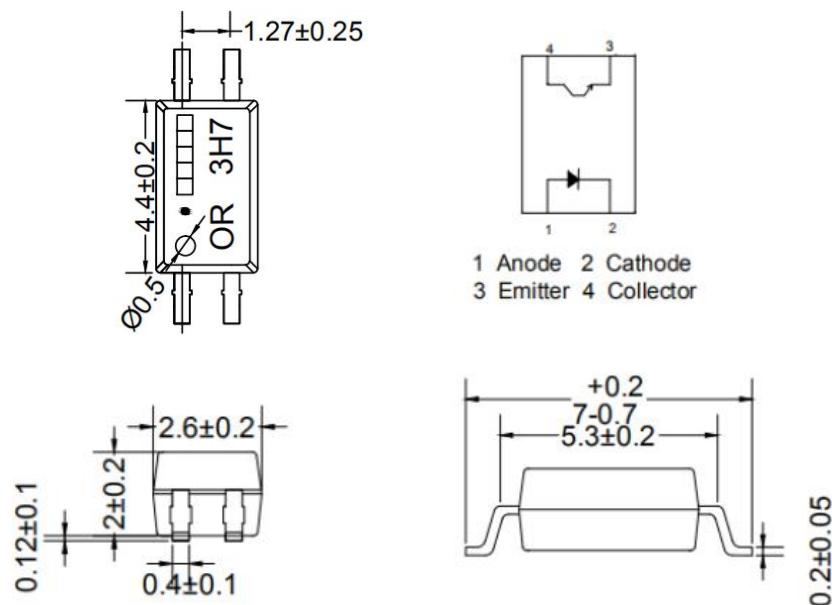
6、Rank table of current transfer ratio CTR

MODEL NO.	CTR Rank	Min.	Max.	Unit	Condition
OR-3H7	A	80	160	%	IF=5mA, V _{CE} =5V, Ta=25°C
	A1	100	160		
	B	130	260		
	C	200	400		
	D	300	600		
	No mark	50	600		

7、Naming Rule

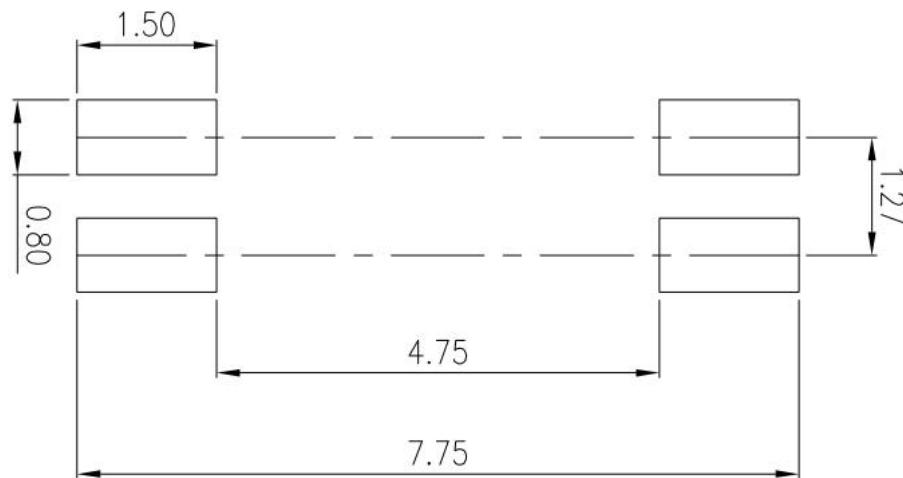


8、Outer Dimension



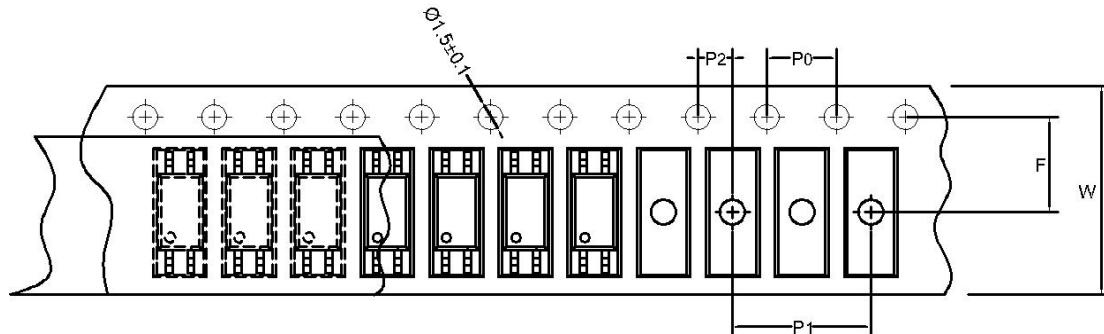
9、Recommended Foot Print Patterns (Mount Pad))

unit : mm

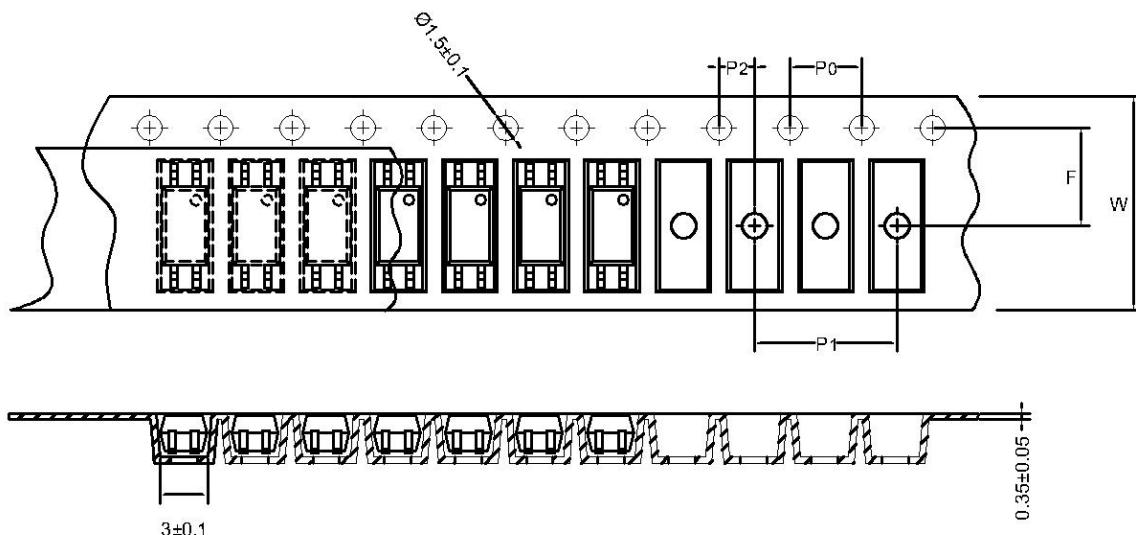


10. Taping Dimensions

(1) .OR-3H7-TP



(2) .OR-3H7-TP1



type	Symbol	Dimensions: mm (in.)
bandwidth	W	12±0.3 (0.47)
pitch	P0	4±0.1 (0.15)
pitch	F	5.5±0.1 (0.217)
	P2	2±0.1 (0.079)
interval	P1	8±0.1 (0.315)

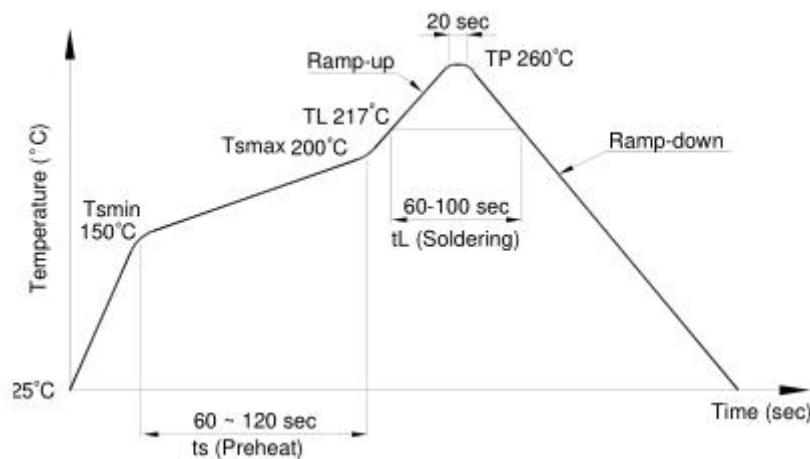
Encapsulation type	OR-3H7
Quantity (pieces)	6000

11. Temperature Profile Of Soldering

(1) .IR Reflow soldering (JEDEC-STD-020C compliant)

One time soldering reflow is recommended within the condition of temperature and time profile shown below.
Do not solder more than three times.

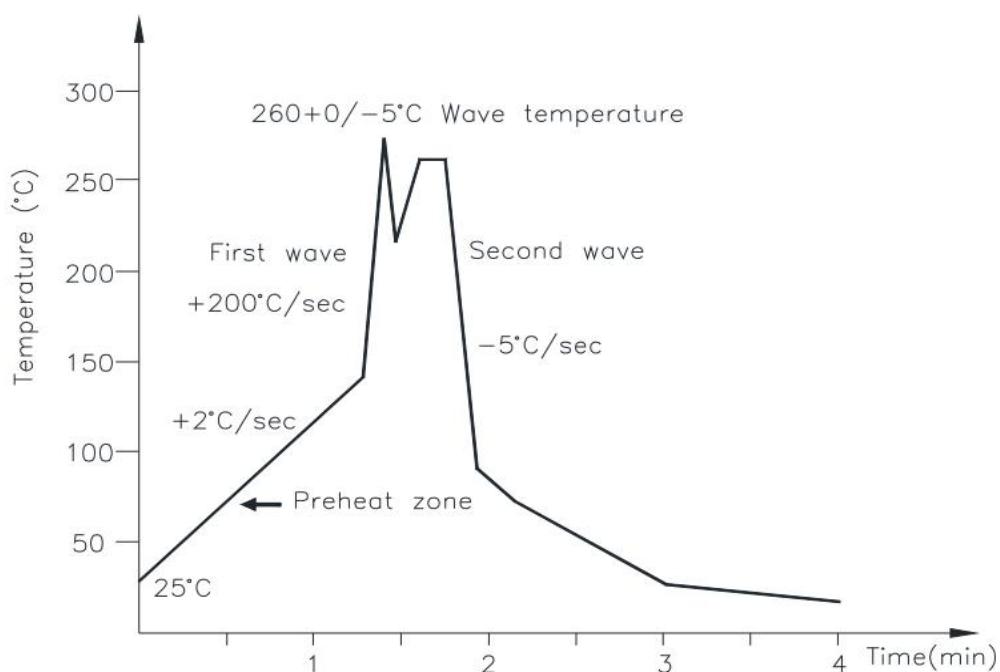
Profile item	Conditions
Preheat	
- Temperature Min (TSmin)	150°C
- Temperature Max (TSmax)	200°C
- Time (min to max) (ts)	90±30 sec
Soldering zone	
- Temperature (TL)	217°C
- Time (tL)	60~100 sec
Peak Temperature	260°C
Ramp-up rate	3°C / sec max.
3°C / sec max.	3~6°C / sec



(2) .Wave soldering (JEDEC22A111 compliant)

One time soldering is recommended within the condition of temperature.

Temperature	260+0/-5°C
Time	10 sec
Preheat temperature	25 to 140°C
Preheat time	30 to 80 sec


(3) .Hand soldering by soldering iron

Allow single lead soldering in every single process. One time soldering is recommended.

Temperature	380+0/-5°C
Time	3 sec max

12. Characteristics Curve

Figure 1. Collector Power Dissipation vs. Ambient Temperature

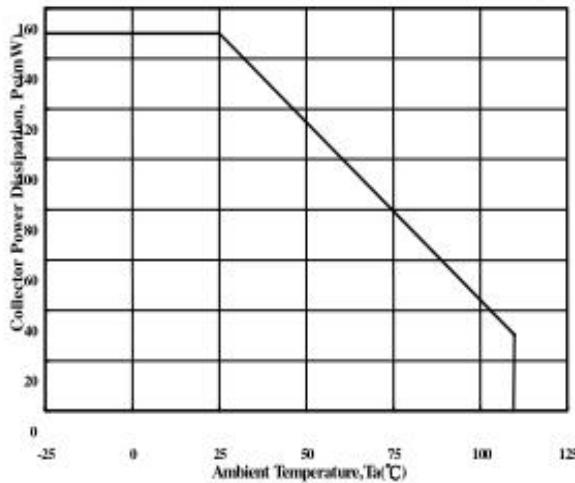


Figure 2. Forward Current vs. Ambient Temperature

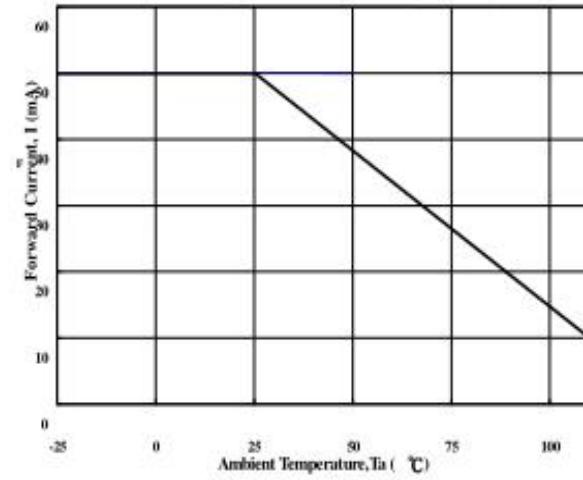


Figure 3. Forward Current vs. Forward Voltage

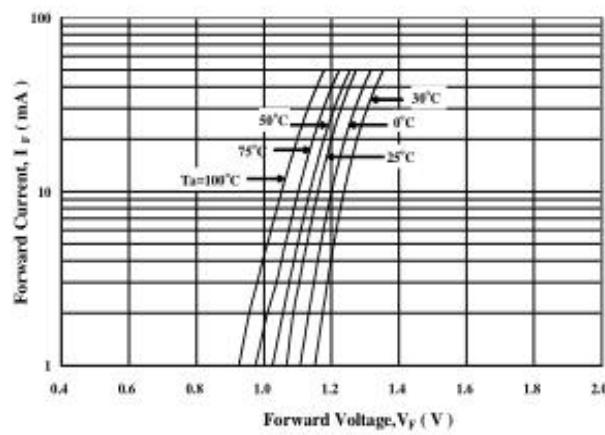


Figure 4. Forward Voltage Temperature Coefficient vs. Forward Current

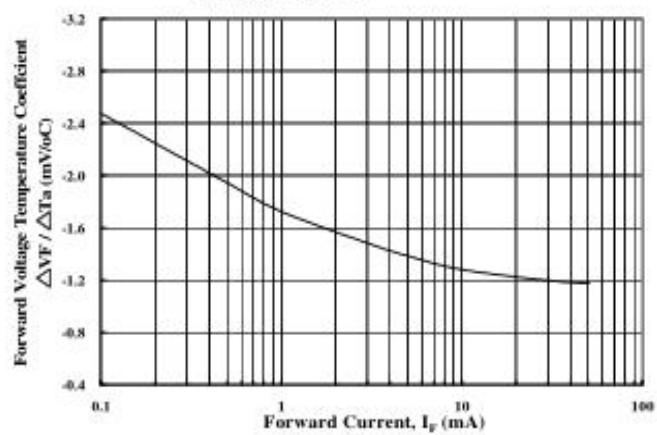


Figure 5. Pulse Forward Current vs. Duty Cycle Ratio

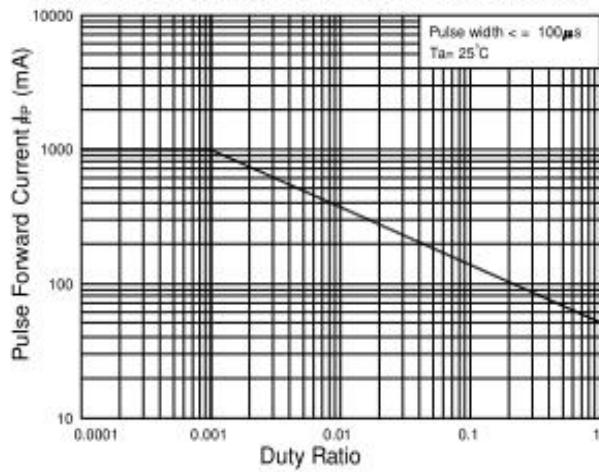


Figure 6. Pulse Forward Current vs. Pulse Forward Voltage

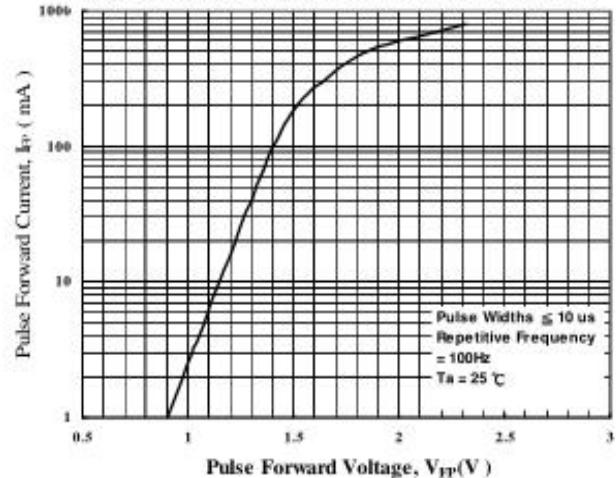


Figure 7. Collector-Emitter Saturation Voltage vs. Forward Current

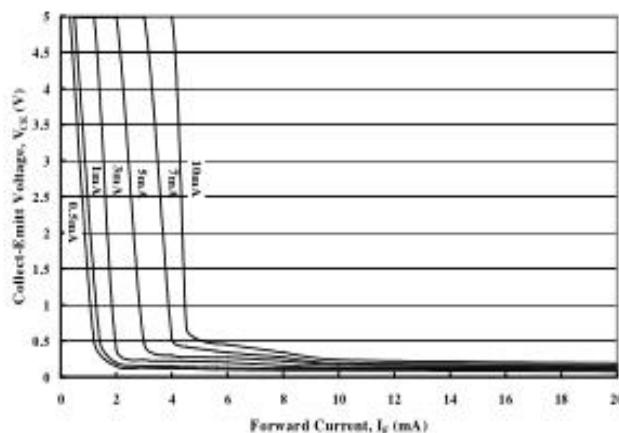


Figure 9. Collector Current vs. Small Collector-Emitter Voltage

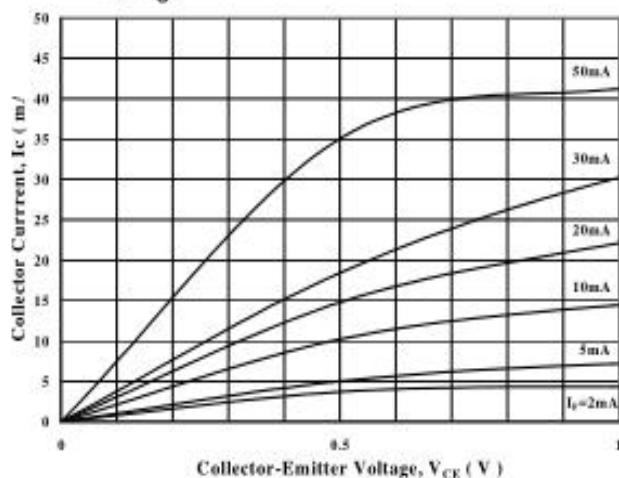


Figure 11. Collector Dark Current vs. Ambient Temperature

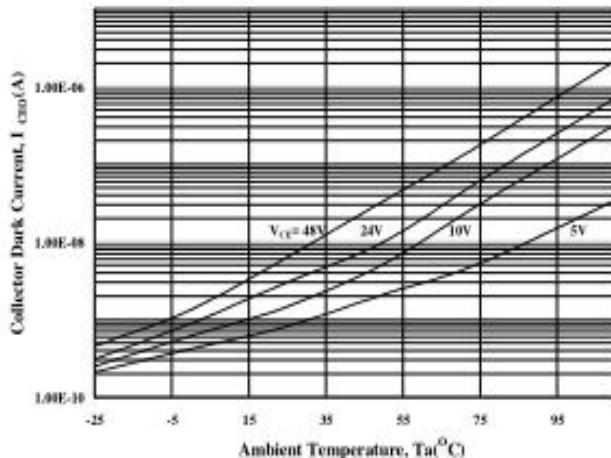


Figure 8. Collector Current vs. Collector-Emitter

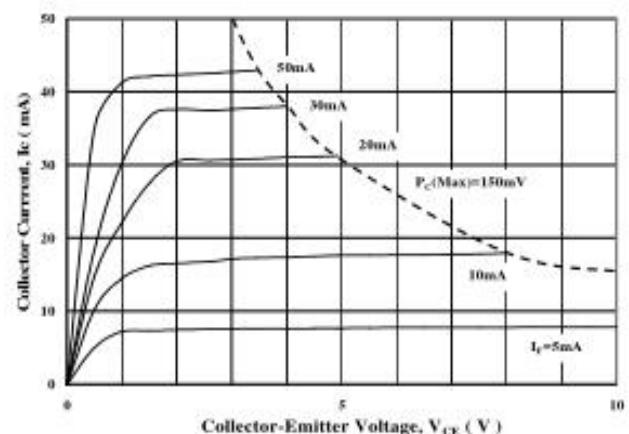


Figure 10. Normalized CTR vs. Forward Current

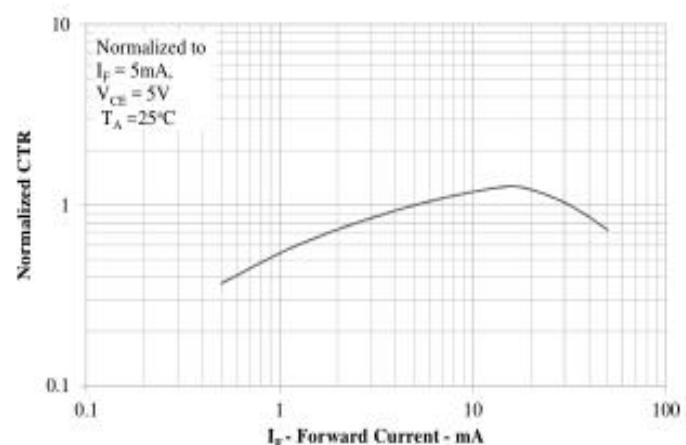


Figure 12. Current Transfer Ratio vs. Forward Current

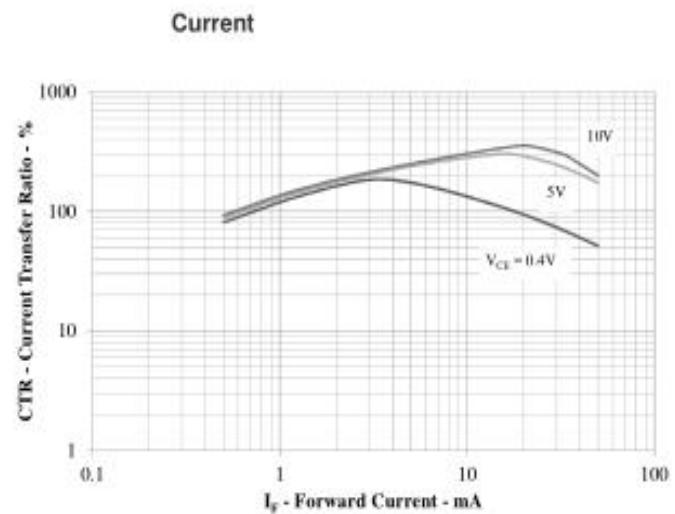


Figure 13. Normalized CTR vs. Ambient Temperature

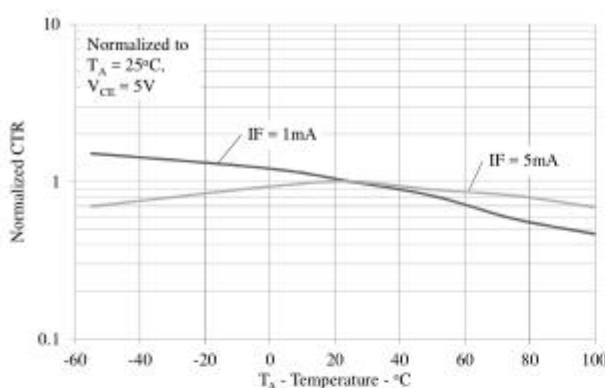


Figure 14. Collector-Emitter Saturation Voltage vs. Ambient Temperature

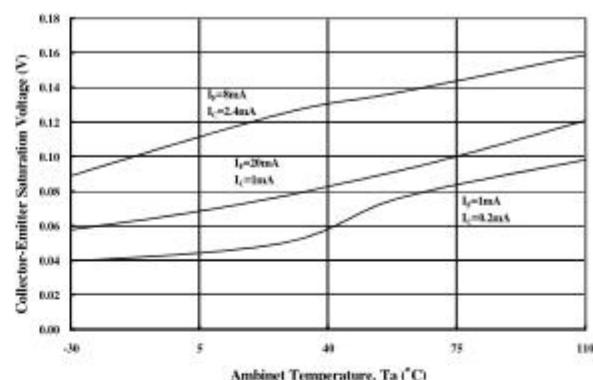


Figure 15. Collector Current vs. Ambient Temperature

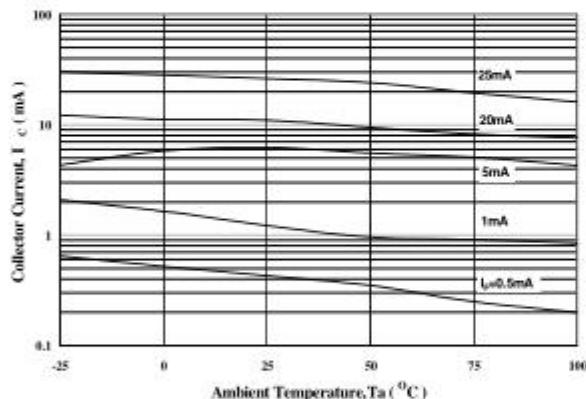


Figure 17. Switching Time vs. Ambient Temperature

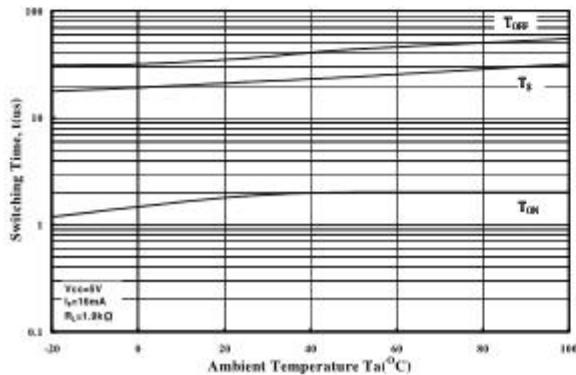


Figure 16. Switching Time vs. Load Resistance

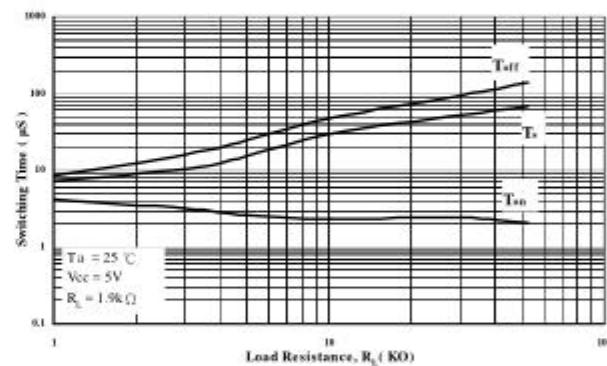


Figure 18. Frequency Response

